



SOT1936-1

HX2QFN14, plastic thermal enhanced super thin quad flat package; no leads; 14 terminals; 3.5 mm x 3.5 mm x 0.32 mm body

7 March 2018

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HX2QFN14
Package type industry code	HX2QFN14
Package style descriptive code	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	24-7-2017
Manufacturer package code	SOT1936-1

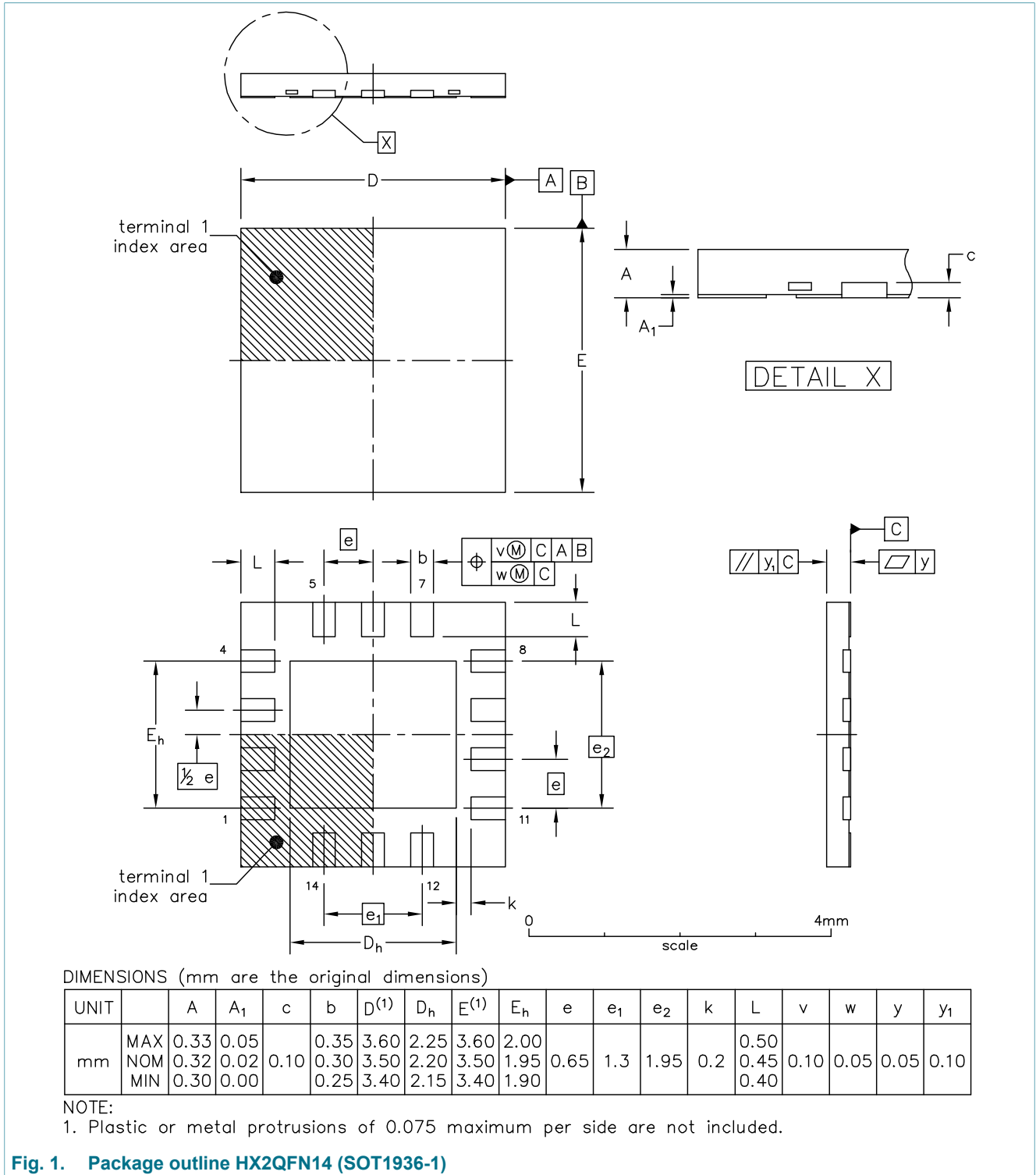
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.4	-	3.5	3.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	0.3	-	0.32	0.33	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	14	-	A/A



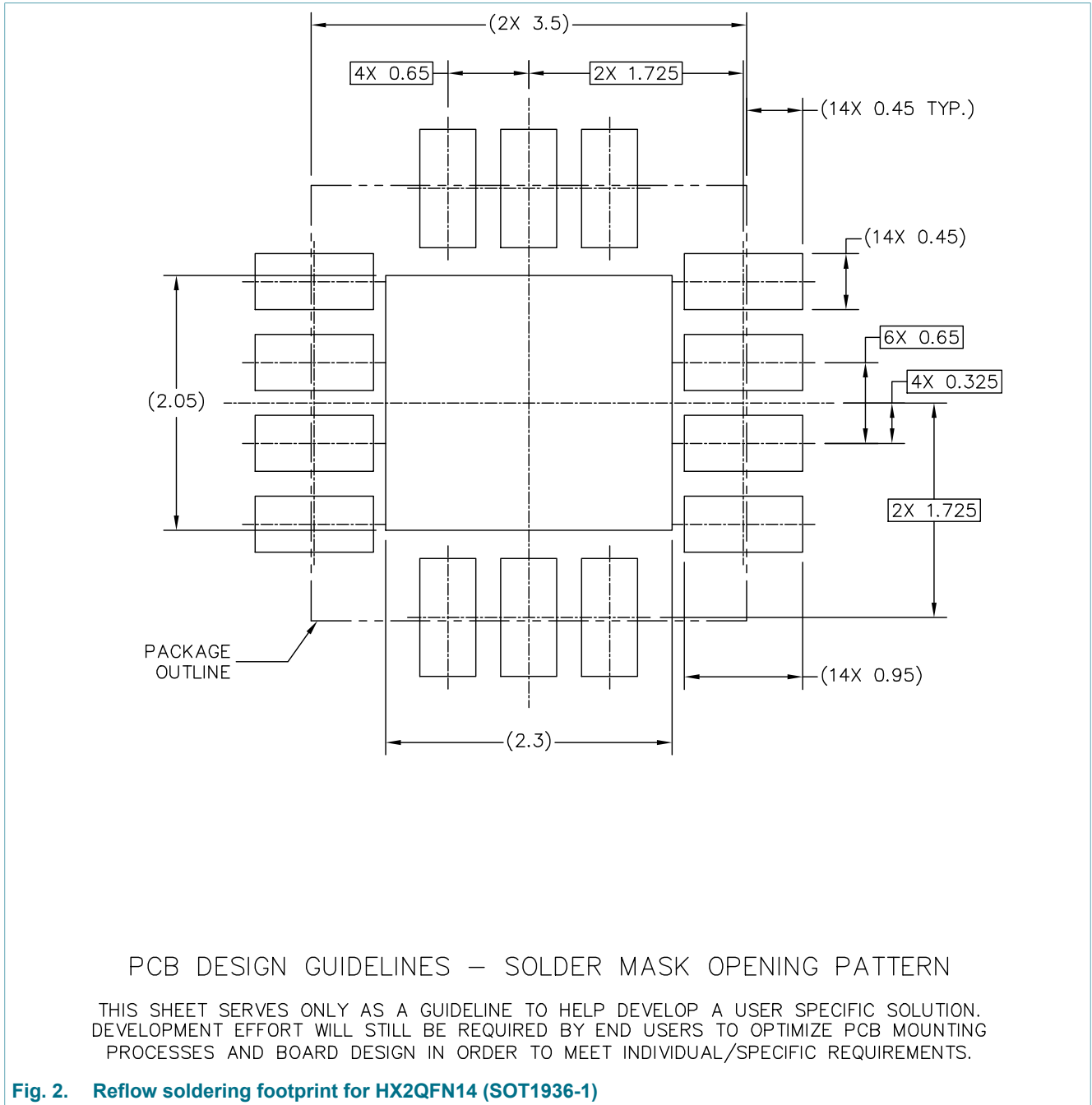
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2. Package outline

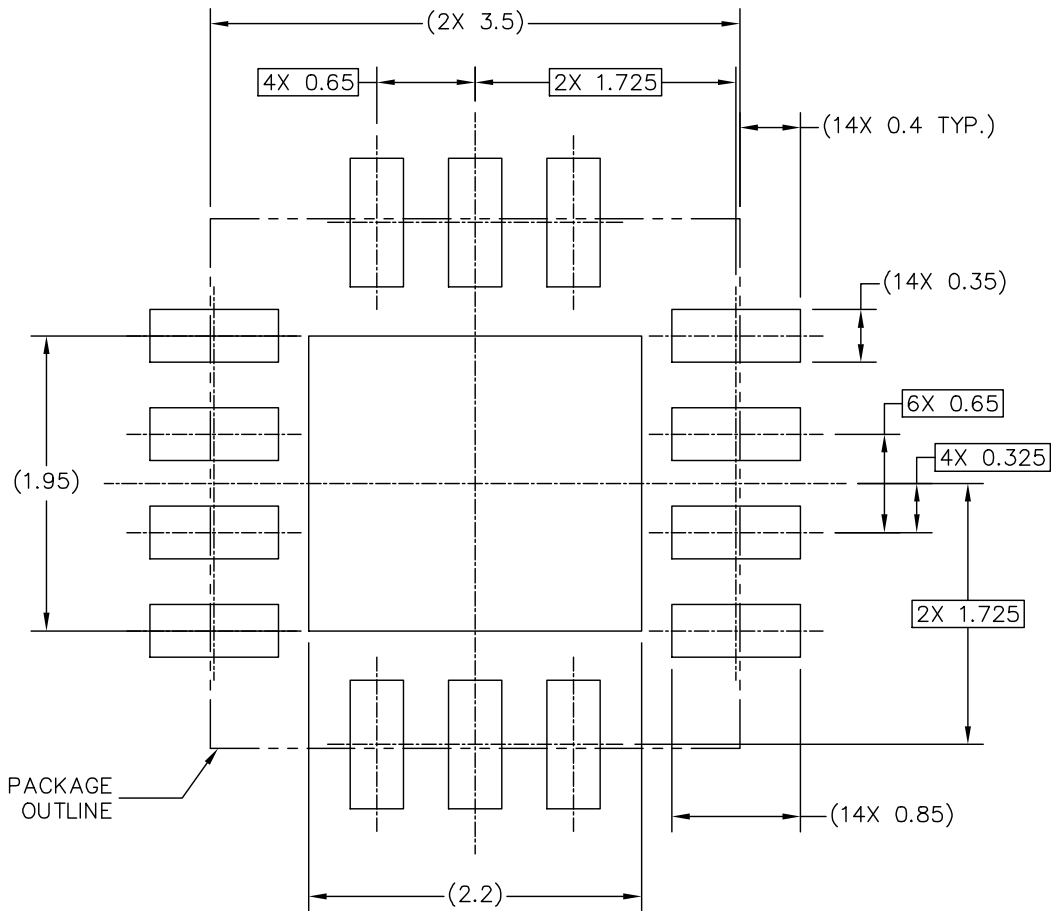


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3. Soldering



HX2QFN14, plastic thermal enhanced super thin quad flat package; no leads; 14 terminals; 3.5 mm x 3.5 mm x 0.32 mm body

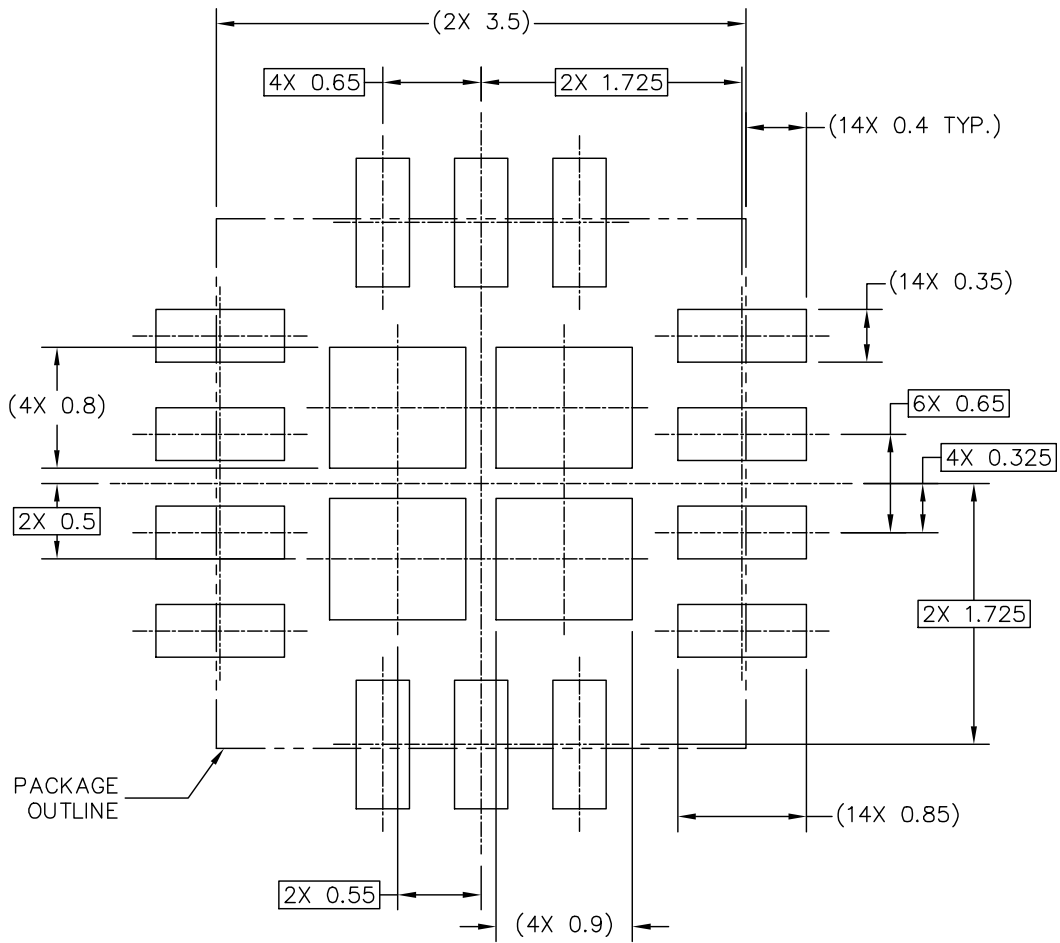


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Fig. 3. Reflow soldering footprint part2 for HX2QFN14 (SOT1936-1)

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RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 4. Reflow soldering footprint part3 for HX2QFN14 (SOT1936-1)

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4. Legal information

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